

INSERT-MOLDABLE HEAT SPREADER, SEMICONDUCTOR DEVICE
USING SAME, AND METHOD FOR MANUFACTURING
SUCH SEMICONDUCTOR DEVICE

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ABSTRACT OF THE DISCLOSURE

10 A heat spreader adapted to be insert-molded with
resin on a surface of a circuit board on which a
semiconductor chip is mounted so that the heat spreader
covers the surface of the circuit board including an
upper surface of the semiconductor chip over
15 substantially a same area as that covered with molded
resin when insert-molded with resin. The heat spreader
has a main-portion which defines a larger gap with
respect to the surface of the circuit board when insert-
molded with resin and a sub-portion which defines a
20 smaller gap with respect to the surface of the circuit
board when insert-molded with resin. The sub-portion is
embedded in the mold resin when insert-molded with resin
so that the heat spreader is strongly adhered to the
resin.